ENVIRONMENTAL AND PACKAGE TESTING DATA FOR QSOP-36					
Stress	**Sample Size**	**Device Hr./Cyc**	**Condition**	**Total Fails**	**Fail Percentage**
BOND INT	62	33,696	150°C	0	0.00
HAST	165	22,000	130°C, 85%RH	0	0.00
Solder Dunk	55	550	260°C, 10 SEC.	0	0.00
Pressure Pot	165	26,400	121°, 15 PSIG	0	0.00
Solderability	16	320	883 M2003	0	0.00
Temp Cycle	415	268,785	−65°C−150°C	0	0.00